

ZIITEK ELECTRONIC MATERIAL & TECHNOLOGY CO., LTD

TIF[™]100-30-02US Thermally Conductive Gap Filler Pads Series

electronic components.

Color

Construction

Outgassing (TML)

Flame Rating

TIFTM100-30-02US Series thermally conductive interface materials are applied to fill the air gaps between the heating elements and the heat dissipation fins or the metal base. Their flexibility and elasticity make them suited to coat very uneven surfaces. Heat can transmit to the metal housing or dissipation plate from the heating elements or even the entire PCB, which effecitly enhances the efficiency and life-time of the heat-generating

Typical Properties of TIF[™]100-30-02US Series

Gray

Ceramic filled silicone elastomer

REV02

Visual

ASTM E595

UL E331100



Features

- » Good thermal conductivity: 3.0 W/mK
- » Naturally tacky needing no further adhesive coating
- Soft and Compressible for low stress applications
- » Available in varies thickness

Application

- Cooling components to the chassis of frame
- » Set Top Box
- Car Battery & Power Supply
- » Charging Pile

Tel:+001-604-2998559

- » LED TV/ Lighting
- » Graphics Card Thermal Module

psi. vs.Thermal Resistance

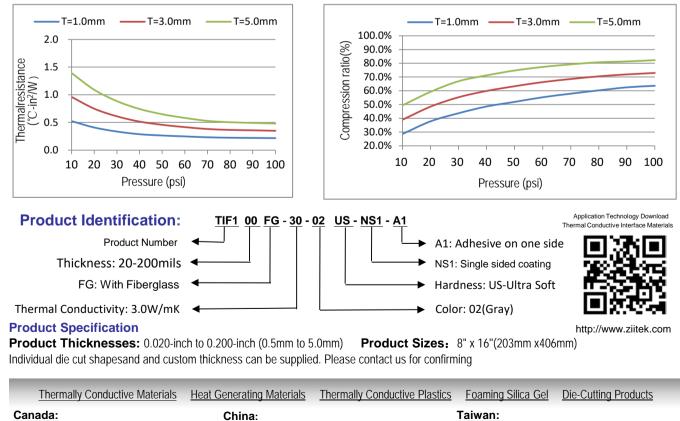
Thickness range 0.020"(0.5mm)~0.200" (5.0mm) ASTM D374 Hardness 20 Shore 00 **ASTM 2240** Specific Gravity 2.9 g/cc ASTM D297 ****** Operating Temp -40 ~160 ℃ Dielectric Breakdown Voltage >5500 VAC ASTM D149 3.8 MHz **Dielectric Constant@1MHz** ASTM D150 1.0X10¹² Ohm-cm Volume Resistivitv ASTM D257 3.0 W/mK **ASTM D5470** Thermal Conductivity 3.0 W/mK GB-T32064

psi. vs. Compression Ratio

Tel:+886-2-22771007

0.35%

94 -V0



E-mail: sales@thermazig.com The information and testing to determine the suitability for their own particular purpose of any information or products referred to herein. E-mail: frances@ziitek.com.tw E-mail: frances@ziitek.com.tw

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